

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-11 have been canceled and claims 12-22 have been added as follows:

Listing of Claims:

Claims 1-11 (canceled)

Claim 12 (new): An electrically conductive contact holder comprising a supporting member, with a contacting surface corresponding to a terminal surface of a to-be-contacted member on which a plurality of external connecting terminals are arranged, a plurality of electrically conductive contacts being arranged on the contacting surface to be electrically connected to the external connecting terminals and accommodated in holder holes, wherein the supporting member includes

a high thermal expansion supporting frame with a coefficient of linear expansion higher than that of the to-be-contacted member; and

a low thermal expansion supporting frame that is arranged adjacent to the high thermal expansion supporting frame in a direction normal to the contacting surface, and has a coefficient of linear expansion lower than that of the to-be-contacted member.

Claim 13 (new): The electrically conductive contact holder according to claim 12, wherein the high thermal expansion supporting frame and the low thermal expansion supporting frame are formed so that a coefficient of linear expansion of the supporting member, defined based on the

thickness in the normal direction and the coefficient of linear expansion of each of the high thermal expansion supporting frame and the low thermal expansion supporting frame, corresponds to the coefficient of linear expansion of the to-be-contacted member.

Claim 14 (new): The electrically conductive contact holder according to claim 12, wherein the supporting member is formed so that the distribution of the coefficient of linear expansion thereof is symmetrical about a midplane in the normal direction to the contacting surface.

Claim 15 (new): The electrically conductive contact holder according to claim 12, wherein the supporting member further includes

an opening at a region where the electrically conductive contacts are arranged; and
a holder hole forming unit that is set in the opening to form the holder holes therein.

Claim 16 (new): An electrically conductive contact holder comprising:
a supporting member with an opening formed therein; and
an holder hole forming unit set in the opening that includes a holder hole accommodating an electrically conductive contact electrically connected to an external connecting terminal provided on a to-be-contacted member, wherein

any one of the supporting member and the holder hole forming unit has a coefficient of linear expansion higher than that of the to-be-contacted member, while the other has a coefficient of linear expansion lower than that of the to-be-contacted member.

Claim 17 (new): The electrically conductive contact holder according to claim 16, wherein the supporting member is formed of a plurality of plate members having different coefficients of linear expansion, which are stacked in layers in the thickness direction.

Claim 18 (new): An electrically conductive contact unit with a contacting surface opposed to a to-be-contacted member, the electrically conductive contact unit comprising:

an electrically conductive contact that is arranged on the contacting surface to be electrically connected to an external connecting terminal provided on the to-be-contacted member in use;

a supporting member that includes a high thermal expansion supporting frame with a coefficient of linear expansion higher than that of the to-be-contacted member, and a low thermal expansion supporting frame that is arranged adjacent to the high thermal expansion supporting frame in a direction normal to the contacting surface and has a coefficient of linear expansion lower than that of the to-be-contacted member; and

a circuit board that is electrically connected to the electrically conductive contact and generates an electric signal supplied to the to-be-contacted member.

Claim 19 (new): The electrically conductive contact unit according to claim 18, wherein the high thermal expansion supporting frame and the low thermal expansion supporting frame are formed so that a coefficient of linear expansion of the supporting member, defined based on the thickness in the normal direction and the coefficient of linear expansion of each of the high thermal expansion supporting frame and the low thermal expansion supporting frame, corresponds to the

coefficient of linear expansion of the to-be-contacted member, and that the distribution of the coefficient of linear expansion thereof is symmetrical about a midplane in the normal direction to the contacting surface.

Claim 20 (new): An electrically conductive contact unit with a contacting surface opposed to a to-be-contacted member, the electrically conductive contact unit comprising:

electrically conductive contacts that are arranged on the contacting surface to be electrically connected to external connecting terminals provided on the to-be-contacted member, respectively, in use;

a holder hole forming unit where holder holes are formed to accommodate the electrically conductive contacts;

a supporting member that supports the holder hole forming unit; and

a circuit board that is electrically connected to the electrically conductive contacts and generates an electric signal supplied to the to-be-contacted member, wherein

the holder hole forming unit and the supporting member are formed so that one thereof has a coefficient of linear expansion higher than that of the to-be-contacted member, while the other has a coefficient of linear expansion lower than that of the to-be-contacted member.

Claim 21 (new): A method for manufacturing an electrically conductive contact holder including a supporting member formed by stacking a plurality of plate members in layers and a holder hole forming unit set in an opening formed in the supporting member, in which holder holes

are formed in the holder hole forming unit to accommodate electrically conductive contacts that are electrically connected to external connecting terminals provided on a to-be-contacted member, respectively, the method comprising:

forming openings in the respective plate members;

forming the supporting member by joining the plurality of the plate members formed with the openings in the thickness direction;

fixing the holder hole forming unit to the inner surface of the opening in the supporting member; and

forming the holder holes in the holder hole forming unit.

Claim 22 (new): The method for manufacturing an electrically conductive contact holder according to claim 21, wherein

the plate members are joined together by diffusion bonding,

the holder hole forming unit is fixed by soldering, and

the forming of the supporting member is performed simultaneously with the fixing.